ABSTRACT

The present invention provides a wiring board in which electronic components are embedded by means of an embedding resin which attains a high mounting density of the electronic components in the wiring board, which exhibits excellent electrical properties such as insulating property, which prevents random reflection of light, and which reduces non-uniformity in color of the resin during curing thereof. The present invention includes a wiring board in which electronic components are embedded by use of an embedding resin having a dielectric constant of less than or equal to about 5 and tanδ of less than or equal to about 0.08. The embedding resin preferably contains carbon black in an amount of less than or equal to about 1.4 mass%. Moreover, the embedding resin preferably contains at least a thermosetting resin and at least one inorganic filler.

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